

Serial No. 08/825,400

Please add the following claim.

B2      Am12.      A circuit board comprising:  
                 a substrate having a joining surface; and  
                 a plurality of solder bumps disposed on said joining  
surface of said substrate in such a manner as to form a  
predetermined profiled line or surface pattern;  
                 wherein said solder bumps have tops which are unconnected,  
flat and leveled.-{

IN THE DRAWINGS:

By way of a separate letter attached hereto, Applicant proposes to amend Figs. 15a and 15b indicated in red on the attached sheet. With the Examiner's approval, the change will be incorporated into the formal drawings.